We Claim:

1. A method for encapsulating an electronic component, which comprises:

providing a component with a coating of a flowable coating material;

hardening the material of the coating; and

completely encapsulating the assembly of the component and the coating in plastic.

2. The method according to claim 1, which further comprises applying the coating material to the component by immersion.

3. The method according to claim 1, which further comprises carrying out the coating providing step by immersing the component in the coating material.

4. The method according to claim 1, which further comprises applying the coating material to the component by spraying.

5. The method according to claim 1, which further comprises carrying out the coating providing step by spraying the coating material on the component.

6. The method according to claim 1, which further comprises:

joining a plurality of components together; and

carrying out the coating providing step by coating the plurality of components at the same time.

7. The method according to claim 1, which further comprises:

joining a plurality of components together; and

carrying out the coating providing step by coating the plurality of components sequentially.

8. The method according to claim 1, which further comprises carrying out the coating providing step by applying the coating material to the component by several successive coating operations.

9. The method according to claim 1, which further comprises carrying out the hardening step by supplying external heat.

10. The method according to claim 1, which further comprises carrying out the hardening step by heating the coating.

11. The method according to claim 1, which further comprises carrying out the hardening step by drying under environmental conditions.

12. The method according to claim 1, which further comprises providing coating material of the coating with a high coefficient of expansion and good adhesion properties.

13. The method according to claim 12, which further comprises selecting the coating material from a plastic selected from the group consisting of polyurethane and silicone.

14. The method according to claim 1, which further comprises selecting the coating material from a plastic selected from the group consisting of polyurethane and silicone.

15. The method according to claim 1, which further comprises subjecting the assembly including the component and the coating to at least one further process operation before carrying out the plastic encapsulating step.

16. The method according to claim 1, which further comprises carrying out the plastic encapsulating step by injection molding the assembly with PBT.

17. The method according to claim 1, which further comprises carrying out the plastic encapsulating step by encapsulating the assembly by injection molding PBT.

18. An electronic component, comprising:

a coating encapsulation of a flowable and hardened coating material; and

a plastic encapsulation encapsulating said coating.

19. An electronic component, comprising:

a component body;

a coating encapsulating said body, said coating being of an originally flowable and later hardened material; and

a plastic encapsulation encapsulating said coating.

20. An electronic component, comprising:

a coating encapsulation being of coating material applied in a flowable condition and hardened; and

a plastic encapsulation encapsulating said coating.